

What is claimed is:

1. A high-frequency ceramic package, comprising;  
a first metal plate forming a substantially rectangular shape, said first metal having fixing cutouts defined at both ends in a longitudinal direction thereof and further having a hollowed portion formed at a central portion thereof,

a second metal plate being fitted in said hollowed portion of said first metal plate in a state in which said first and second metal plates are jointed in a end to end relationship, and

a ceramic frame plate brazed to a jointed metal plate on a peripheral surface of said jointed metal plate, said jointed metal plate including said first and second metal plates,

wherein a cavity defined between said second metal plate and said ceramic frame plate has a semiconductor electronic component mounting portion on a bottom of said cavity, said first metal being close to said ceramic frame plate in thermal expansion coefficient, said second metal plate being made from a material having an elevated degree of heat-sinking characteristics.

2. A high-frequency ceramic package as defined in claim 1, wherein said ceramic frame plate is brazed to said first and second metal plates in a state of being disposed across respective surfaces of said first and second metal plates along portion where said first and second metal plates are jointed together.

3. A high-frequency ceramic package as a defined in

claim 1, wherein said ceramic frame plate is brazed to said first metal plate.

4. A high-frequency ceramic package as defined in claim 1, wherein said first metal plate is made from one of KV and 42 alloy, said second metal plate being made from a jointed plate having three layers of Copper-Molybdenum-Copper.

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